



High-Reliability Semiconductor Devices and Integrated Circuits, 2nd Edition

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Message from the Guest Editors

Dear Colleagues,

In this Special Issue on “High-Reliability Semiconductor Devices and Integrated Circuits”, we will focus on simulation, modeling, design, and optimization for high-reliability devices and integrated circuits for automobiles, avionics, and aerospace. High-reliability devices and integrated circuits are intensely studied because they are widely used in traditional aerospace electronic systems, avionics, automobiles, etc. In recent years, new technologies such as intelligent analysis, optimization, and manufacturing based on artificial intelligence and other novel technologies have brought vitality to the field of high-reliability devices and circuits.

The objective of this Special Issue is to collect research works focused on mathematical models, high-efficiency/-precision numerical solution methods, and intelligent design and optimization methods for high-reliability materials and devices and integrated circuits. We welcome novel works reporting on high-reliability devices and circuits and their applications to discuss the most recent breakthroughs and the potential impacts in related research fields.





Editor-in-Chief

Message from the Editor-in-Chief

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